## **Supporting Information**

## Interface engineering for suppression of flat-band voltage shift in the solution-processed ZnO / polymer dielectric thin film transistor

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Table S1. Definition of the variables used in the analytic model.

Variables	Definition	Values	Units
W	Width of the channel	1000	μm
L	Length of the channel	50	μm
V <sub>G</sub>	Gate bias voltage	-	
V <sub>D</sub>	Voltage at the drain electrode	30	V
V <sub>S</sub>	Voltage at the source electrode	0	V
$C_i$	Capacitance of the gate-insulator per	9.00	nF cm <sup>-2</sup>
	unit area		
Es	Relative electrical permittivity in ZnO	7.5	-
n <sub>0</sub>	Charge-carrier number of ZnO per unit	10 <sup>19</sup>	cm <sup>-3</sup>
	volume		
Т	Temperature of the device	298	K
$V_{FB}$	Flat-band voltage Fitting parame		V
$T_0$	Trap characteristic temperature	Fitting parameter	K
$N_t$	Total number of trap state per unit	Fitting parameter	cm <sup>-3</sup>
	volume at $T$		
$\sigma_{_0}$	Conductivity of ZnO at infinite	Fitting parameter	S cm <sup>-1</sup>
	temperature		

	ZnO/SAIL/PVP TFT		ZnO/PVP TFT		Units
	Forward	Backward	Forward	Backward	
V <sub>FB</sub>	0.009	0.499	-2.742	6.014	V
$T_0$	553	553	550	552	K
N <sub>t</sub>	2.95*10 <sup>19</sup>	2.94*10 <sup>19</sup>	2.53*10 <sup>19</sup>	2.10*10 <sup>19</sup>	cm <sup>-3</sup>
$\sigma_0$	2.23	2.35	2.25	2.99	S cm <sup>-1</sup>

## *Table S2.* Values of fitting parameters used for the simulation in Figure 5.



**Figure S1.** HR-TEM images of solution processed ZnO semiconductor on polymer dielectric layer were shown. (a) The poly crystalline ZnO semiconductor was well deposited on the highly cross linked PVP, c-PVP, dielectric layer with 629 nm thickness. (b) The flexible gate & substrate was fabricated with 20 nm ITO on the polyester (PET) film.



**Figure S2.** (a) Cross-sectional HR-TEM image of solution processed ZnO semiconductor on polymer dielectric layer were shown. (b) The solution processed ZnO shows crystalline FFT-SAED patterns.



**Figure S3.** 3D views of AFM images: (a) 3D view of ZnO thin film on PVP without interface engineering (RMS=5.33 nm), (b) 3D view of intrinsic ZnO thin film on PVP with interface engineering (RMS= 2.92 nm)



**Figure S4.** Voltage-dependent capacitance of both the SAIL coated PVP and the intrinsic PVP at 100 kHz.



**Figure S5.** Cross-sectional SEM images of polymer dielectric layers were shown. (a) The thickness of spin-coated PVP at 2000 rpm was 598 nm. (b) The thickness spin-coated TPC at 2000 rpm was 137 nm. (c) The thickness of spin-coated double dielectric layer was 615 nm that is the sum of TPC and PVP layer by spin-coating at 2000 rpm.



**Figure S6.** The  $I_{DS}^{1/2} - V_G$  transfer curves of the flexible ZnO/SAIL/PVP TFT in accordance with before and during bending.



**Figure S7.** Optical spectroscopy images: (a) the ITO PET before bending; (b) the ITO PET after bending. (C) The ZnO/SAIL/PVP TFT was shown reliable flexibility without any delamination after bending.